

UCC5610

18-LINE 3-5 VOLT LOW CAPACITANCE SCSI ACTIVE TERMINATOR

SLUS362A – FEBRUARY 1997 – REVISED NOVEMBER 2000

description (continued)

The power amplifier output stage allows the UCC5610 to source full termination current and sink active negation current when all termination lines are actively negated.

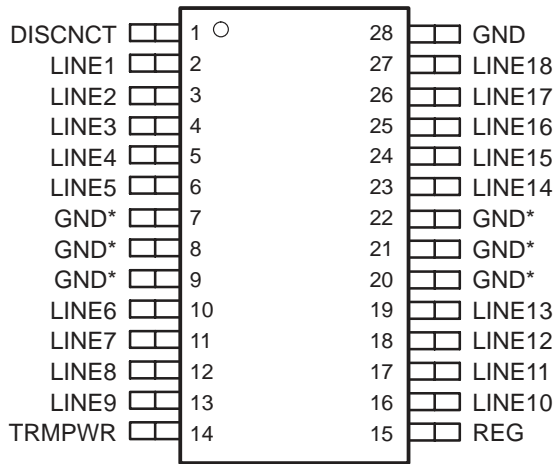
The UCC5610 is pin for pin compatible with Unitrode's other 18-line SCSI terminators, allowing lower capacitance and lower voltage upgrades to existing systems. The UCC5610, as with all Unitrode terminators, is completely hot-pluggable and appears as high impedance at the terminating channels with VTRMPWR = 0 V or open.

Internal circuit trimming is utilized, first to trim the 110-Ω termination impedance to a 7% tolerance, and then most importantly, to trim the output current to a 4% tolerance, which maximizes noise margin.

Other features include thermal shutdown and current limit.

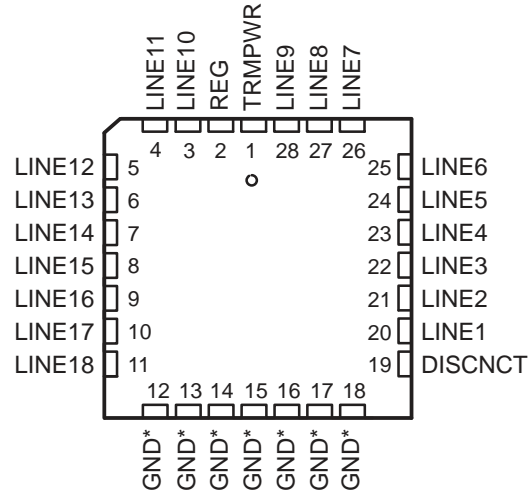
This device is offered in low thermal resistance versions of the industry standard 28-pin wide body SOIC and 28-pin PLCC.

**DWP PACKAGE
TOP VIEW**



* DWP package pin 28 serves as signal ground; pins 7, 8, 9, 20, 21, 22 serve as heatsink/ground.

**QP PACKAGE
TOP VIEW**



* QP package pins 12-18 serve as both heatsink and signal ground.

AVAILABLE OPTIONS

T _J	PACKAGED DEVICES†	
	SOIC (DWP)	PLCC (QP)
0°C to 70°C	UCC5610DWP	UCC5610QP

† Available tape and reeled. Add TR suffix to device type to order quantities of 1000 devices per reel.

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)^{†‡}

Tempwr voltage	7 V
Signal line voltage	0 V to 7 V
Regulator output current	Self-regulating
Storage temperature	–65°C to 150°C
Operating temperature	–55°C to 150°C
Lead temperature (soldering, 10 Sec.)	300°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[‡] Unless otherwise specified all voltages are with respect to Ground. Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Interface Products Data Book (TI Literature Number SLUD002) for thermal limitations and considerations of packages.

recommended operating conditions

Tempwr voltage	2.75 V to 5.25 V
Signal line voltage	0 V to 5 V
Disconnect input voltage	0 V to Tempwr

electrical characteristics, these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C , $\text{TRMPWR} = 3.3\text{ V}$, $\text{DISCNCT} = 0\text{ V}$, $\text{R}_{\text{DISCNCT}} = 0\ \Omega$, $T_A = T_J$, (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
Tempwr supply current	All termination lines = open		1	2	mA
	All termination lines = 0.2 V		415	455	mA
Power down mode	DISCNCT = tempwr		0.5	5	μA
Output Section (110 Ω – Terminator Lines)					
Terminator impedance	See Note 4	102.3	110	117.7	Ω
Output high voltage	See Note 1	2.5	2.7	3.0	V
Max output current	$V_{\text{LINE}} = 0.2\text{ V}$, $T_J = 25^\circ\text{C}$	–25.4	–23	–22.1	mA
	$V_{\text{LINE}} = 0.2\text{ V}$	–25.4	–23	–21	mA
	$V_{\text{LINE}} = 0.2\text{ V}$, $\text{TRMPWR} = 3\text{ V}$, $T_J = 25^\circ\text{C}$ See Note 1	–25.4	–23	–20.2	mA
	$V_{\text{LINE}} = 0.2\text{ V}$, $\text{TRMPWR} = 3\text{ V}$, See Note 1	–25.4	–23	–19	mA
	$V_{\text{LINE}} = 0.5\text{ V}$			–22.4	mA
Output leakage	DISCNCT = 2.4 V, $\text{TRMPWR} = 0\text{ V to }5.25\text{ V}$		10	400	nA
Output capacitance	DISCNCT = 2.4 V, See Note 2, See Note 3, DWP package		1.8	2.5	pF
Output Section (2.5 kΩ – Terminator Lines) ($\text{R}_{\text{DISCNCT}} = 80\text{ k}\Omega$)					
Terminator impedance		2	2.5	3	k Ω
Output high voltage	$\text{TRMPWR} = 3\text{ V}$, See Note 1	2.5	2.7	3.0	V
Max output current	$V_{\text{LINE}} = 0.2\text{ V}$	–1.4	–1	–0.7	mA
	$V_{\text{LINE}} = 0.2\text{ V}$, $\text{TRMPWR} = 3\text{ V}$, See Note 1	–1.5	–1	–0.6	mA
Output leakage	DISCNCT = 2.4 V, $\text{TRMPWR} = 0\text{ to }5.25\text{ V}$		10	400	nA
Output capacitance	DISCNCT = 2.4 V See Note 2, See Note 3, DWP package		1.8	2.5	pF

- NOTES: 1. Measuring each termination line while other 17 are low (0.2 V).
 2. Ensured by design. Not production tested.
 3. Output capacitance is measured at 0.5 V.
 4. Tested by measuring I_{OUT} with $V_{\text{OUT}} = 0.2\text{ V}$ and $V_{\text{OUT}} = V_{\text{REG}} - 0.1\text{ V}$ then calculating the impedance.



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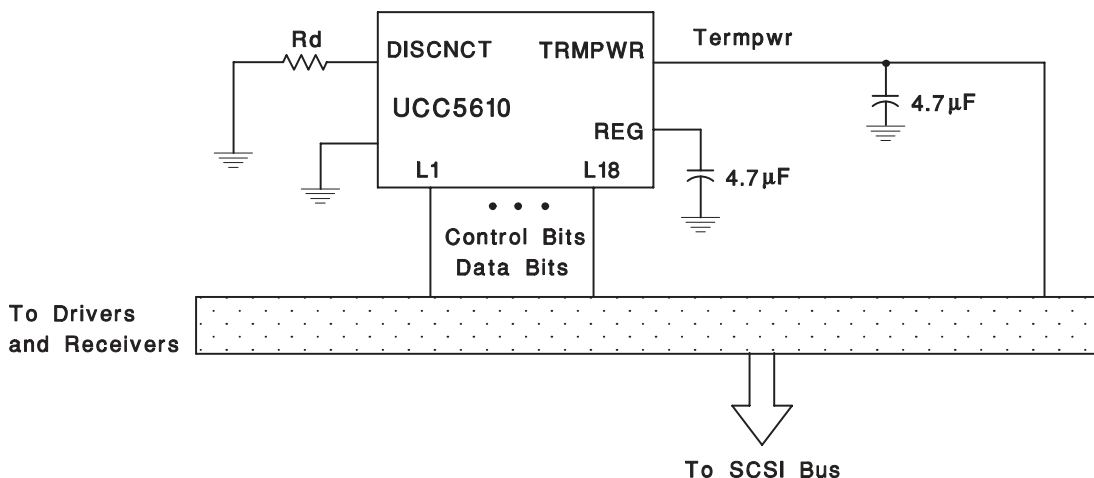
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electrical characteristics, these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C , $\text{TRMPWR} = 3.3\text{ V}$, $\text{DISCNCT} = 0\text{ V}$, $R_{\text{DISCNCT}} = 0\ \Omega$, $T_A = T_J$, (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Regulator Section					
Regulator output voltage	$5.25\text{ V} > \text{TRMPWR} > 3\text{ V}$	2.5	2.7	3.0	V
Drop out voltage	All termination lines = 0.2 V		0.1	0.2	V
Short circuit current	$V_{\text{REG}} = 0\text{ V}$	-800	-650	-450	mA
Sinking current capability	$V_{\text{REG}} = 3\text{ V}$	200	400	800	mA
Thermal shutdown	See Note 2		170		$^\circ\text{C}$
Thermal shutdown hysteresis	See Note 2		10		$^\circ\text{C}$
Disconnect Section					
Disconnect threshold	$R_{\text{DISCNCT}} = 0\ \Omega$ & $80\text{ k}\Omega$	0.8	1.5	2.0	V
Input current	$\text{DISCNCT} = 0\text{ V}$		30	50	μA

NOTES: 2. Ensured by design. Not production tested.

APPLICATION INFORMATION



UDG-94130

Figure 1. Typical SCSI Bus Configurations Utilizing a UCC5610 Device

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
UCC5610DWP	NRND	SOIC	DW	28		TBD	Call TI	Call TI	0 to 70		
UCC5610DWPG4	NRND	SOIC	DW	28		TBD	Call TI	Call TI	0 to 70		
UCC5610DWPTR	NRND	SOIC	DW	28		TBD	Call TI	Call TI	0 to 70		
UCC5610DWPTRG4	NRND	SOIC	DW	28		TBD	Call TI	Call TI	0 to 70		
UCC5610QP	NRND	PLCC	FN	28		TBD	Call TI	Call TI	0 to 70		
UCC5610QPTR	NRND	PLCC	FN	28		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

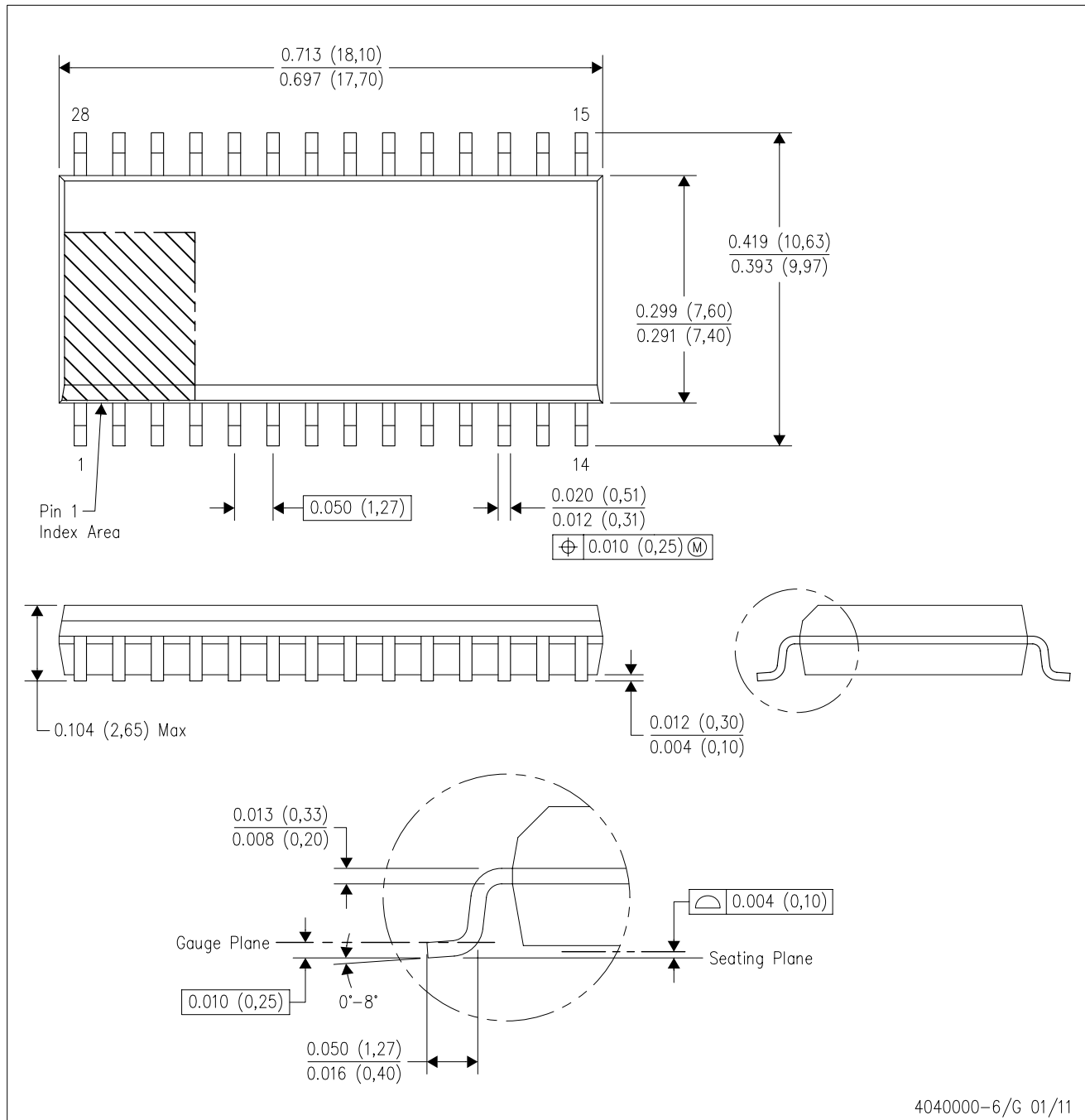
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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DW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AE.

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